

OptiMOS[™]-T2 Power-Transistor





Features

- N-channel Enhancement mode
- AEC qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green Product (RoHS compliant)
- 100% Avalanche tested

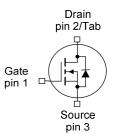
Product Summary

V _{DS}	100	V
$R_{\mathrm{DS(on),max}}$	12	mΩ
I _D	60	Α

PG-TO252-3-313



Туре	Package	Marking
IPD60N10S4L-12	PG-TO252-3-313	4N10L12



Maximum ratings, at T_j =25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I _D	T _C =25°C, V _{GS} =10V	60	Α
		$T_{\rm C}$ =100°C, $V_{\rm GS}$ =10 $V^{1)}$	43	
Pulsed drain current ¹⁾	I _{D,pulse}	T _C =25°C	240]
Avalanche energy, single pulse ¹⁾	E _{AS}	/ _D =30A	120	mJ
Avalanche current, single pulse	IAS	-	40	А
Gate source voltage	V_{GS}	-	+/-16	V
Power dissipation	P_{tot}	T _C =25°C	94	W
Operating and storage temperature	$T_{\rm j},T_{\rm stg}$	-	-55 +175	°C
IEC climatic category; DIN IEC 68-1	-	-	55/175/56	



Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics ¹⁾						
Thermal resistance, junction - case	R_{thJC}		-	-	1.6	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}		-	-	62	
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm ² cooling area ²⁾	-	-	40	

Electrical characteristics, at T_j =25 °C, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	V _{GS} =0V, I _D =1mA	100	-	-	V
Gate threshold voltage	$V_{\rm GS(th)}$	$V_{\rm DS}=V_{\rm GS}, I_{\rm D}=46\mu{\rm A}$	1.1	1.6	2.1	
Zero gate voltage drain current	I _{DSS}	V _{DS} =100V, V _{GS} =0V	-	0.01	1	μΑ
		$V_{\rm DS}$ =100V, $V_{\rm GS}$ =0V, $T_{\rm j}$ =125°C ²⁾	-	1	100	
Gate-source leakage current	I _{GSS}	V _{GS} =20V, V _{DS} =0V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V _{GS} =4.5V, I _D =30A	-	12.3	15	mΩ
		V _{GS} =10V, I _D =60A	-	9.8	12	



Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics ¹⁾						
Input capacitance	Ciss		-	2440	3170	pF
Output capacitance	Coss	$V_{\rm GS}$ =0V, $V_{\rm DS}$ =25V, f =1MHz	-	824	1070	
Reverse transfer capacitance	C _{rss}		-	77	155	
Turn-on delay time	$t_{d(on)}$		-	4	-	ns
Rise time	t _r	$V_{\rm DD} = 50 \text{V}, \ V_{\rm GS} = 10 \text{V},$	-	3	-	
Turn-off delay time	$t_{d(off)}$	$I_{\rm D}$ =60A, $R_{\rm G}$ =3.5 Ω	-	20	-	
Fall time	t_{f}		-	21	-	
Gate Charge Characteristics ¹⁾			T	T	ı	T
Gate to source charge	Q _{gs}		-	8	10	nC
Gate to drain charge	Q_{gd}	V _{DD} =80V, I _D =60A,	-	9	18	
Gate charge total	Q_g	V _{GS} =0 to 10V	-	38	49	
Gate plateau voltage	$V_{ m plateau}$		-	3.5	-	V
Reverse Diode						
Diode continous forward current ¹⁾	Is	T 0500	-	-	60	А
Diode pulse current ¹⁾	I _{S,pulse}	-T _C =25°C	-	-	240	
Diode forward voltage	V_{SD}	V _{GS} =0V, I _F =60A, T _j =25°C	-	1.0	1.3	V
Reverse recovery time ¹⁾	t _{rr}	V_R =50V, I_F =50A, di_F/dt =100A/ μ s	-	70	-	ns
Reverse recovery charge ¹⁾	Q _{rr}		-	150	-	nC

¹⁾ Defined by design. Not subject to production test.

 $^{^{2)}}$ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm 2 (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.



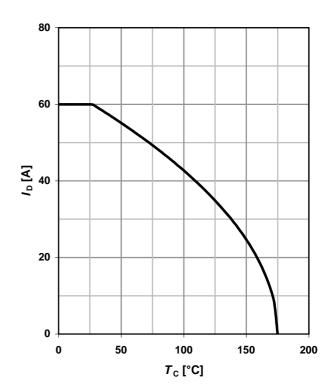
1 Power dissipation

$$P_{\text{tot}} = f(T_{\text{C}}); V_{\text{GS}} \ge 6 \text{ V}$$

100 90 80 70 60 P_{tot} [W] 50 40 30 20 10 0 50 100 150 200 0 T_C [°C]

2 Drain current

$$I_D = f(T_C); V_{GS} \ge 6 \text{ V}$$



3 Safe operating area

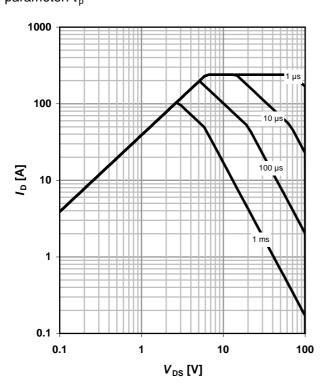
$$I_D = f(V_{DS}); T_C = 25 \text{ °C}; D = 0$$

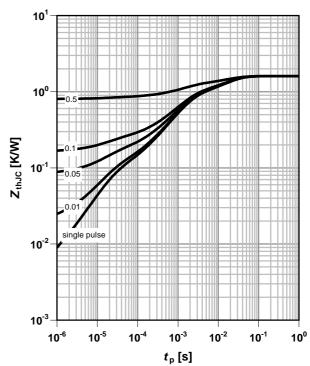
parameter: t_p

4 Max. transient thermal impedance

$$Z_{\rm thJC} = f(t_{\rm p})$$

parameter: $D=t_p/T$



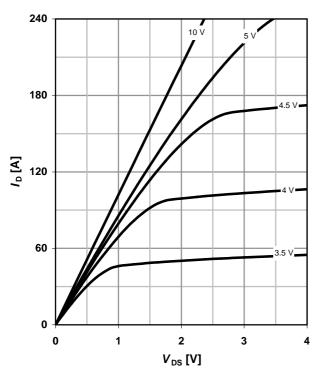




5 Typ. output characteristics

 $I_{\rm D} = f(V_{\rm DS}); T_{\rm j} = 25 \,{}^{\circ}{\rm C}$

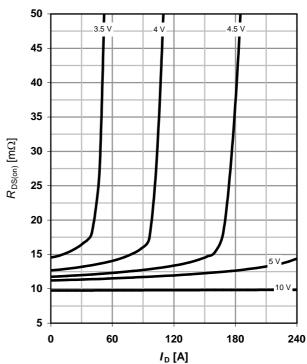
parameter: V_{GS}



6 Typ. drain-source on-state resistance

 $R_{DS(on)} = f(I_D); T_j = 25 \text{ }^{\circ}\text{C}$

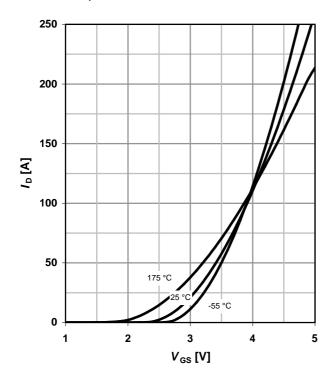
parameter: V_{GS}



7 Typ. transfer characteristics

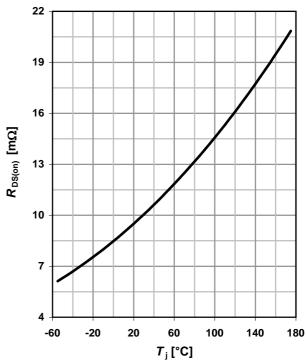
 $I_D = f(V_{GS}); V_{DS} = 6V$

parameter: T_i



8 Typ. drain-source on-state resistance

$$R_{DS(on)} = f(T_j); I_D = 60 \text{ A}; V_{GS} = 10 \text{ V}$$





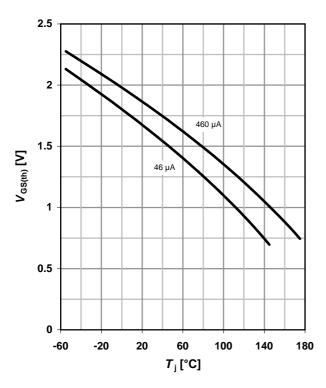
9 Typ. gate threshold voltage

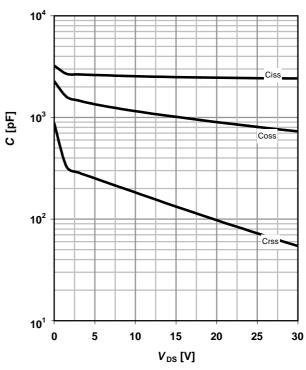
 $V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter: I_D

10 Typ. capacitances

 $C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$





11 Typical forward diode characteristicis

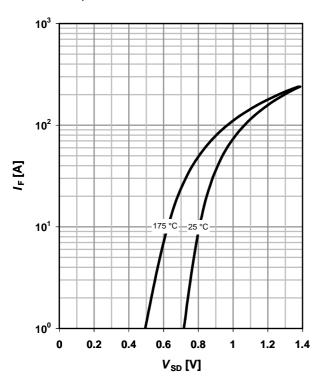
 $IF = f(V_{SD})$

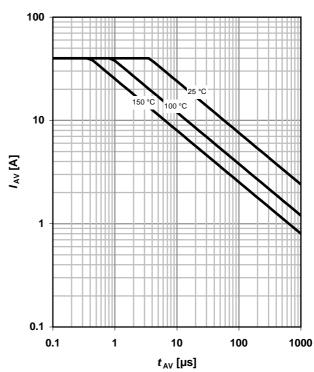
parameter: T_i

12 Avalanche characteristics

 $I_{AS} = f(t_{AV})$

parameter: T_{j(start)}





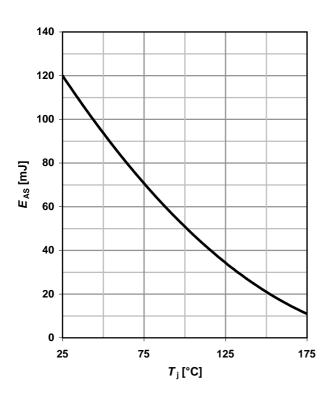


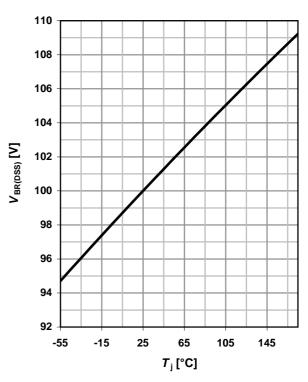
13 Avalanche energy

$$E_{AS} = f(T_i); I_D = 40 A$$

14 Drain-source breakdown voltage

$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$

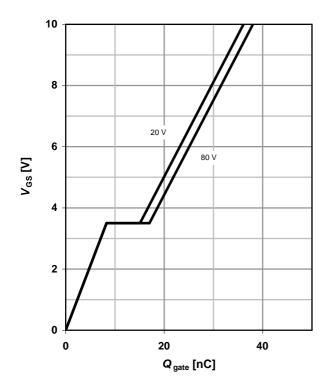




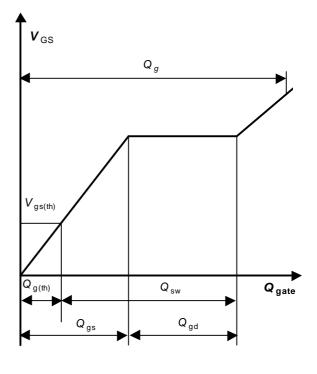
15 Typ. gate charge

 $V_{GS} = f(Q_{gate}); I_D = 60 A pulsed$

parameter: V_{DD}



16 Gate charge waveforms





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Revision History

Version	Date	Changes
Revision 1.0	30.11.2011	Final Data Sheet

Mouser Electronics

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